

(1,27 mm) .050"

SEAF-20-01-L-04-2-RA-GP-TR

SEAF-20-01-L-06-2-RA-GP-TR

SEAF-RA SERIES

HI-DENSITY RIGHT ANGLE OPEN PIN FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAF-RA

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Current Rating:

2.1 A per pin

(4 adjacent pins powered)

Operating Temp Range:

-55°C to +125°C

Plating:

Au or Sn over

50 μ" (1,27 μm) Ni

Contact Resistance:

17.1 mΩ max

Working Voltage:

280 VAC

Mated Cycles:

100

RoHS Compliant:

Yes

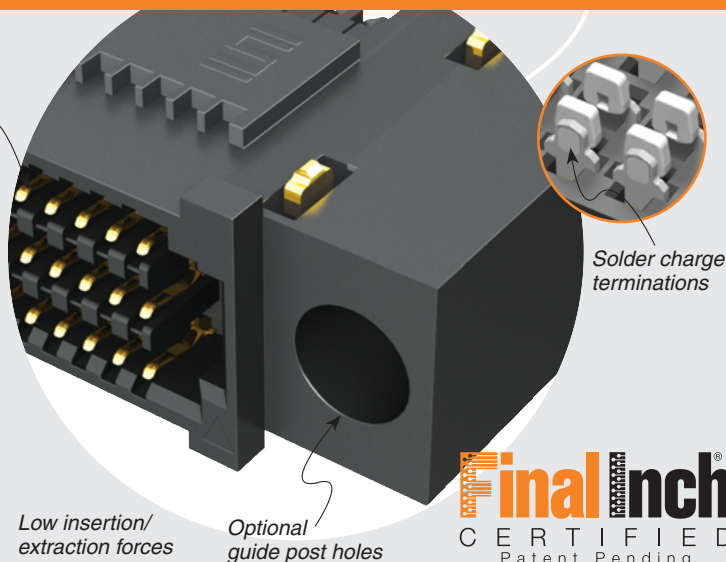
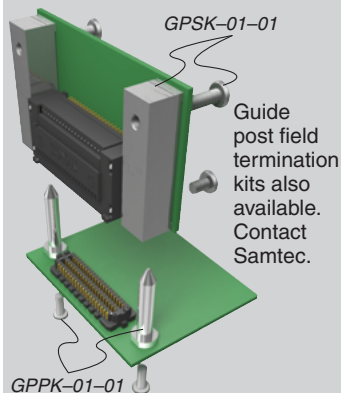
Lead-Free Solderable:

Yes

Mates with:

SEAM, SEAMP, SEAC

OTHER SOLUTIONS



FinalInch
CERTIFIED
Patent Pending

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

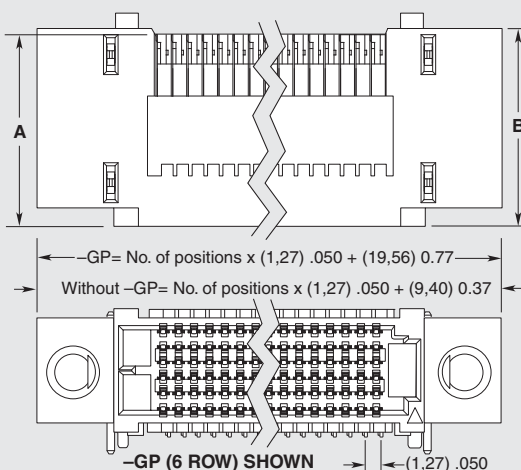
SEAF	NO. PINS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	TR
	-20, -30, -40, -50		-L = 10 μ" (0,25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0,76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08* = Eight Rows -10* = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge		-GP = Guide Post Hole -LP = Latch Post (06 row 30 positions only) (Mates to SEAC Series) -K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

NO. OF ROWS	A	B	C
-04	(13,26) .522	(13,77) .542	(7,91) .311
-06	(15,80) .622	(16,31) .642	(10,45) .411
-08	(18,34) .722	(18,85) .742	(12,99) .511
-10	(20,88) .822	(21,39) .842	(15,53) .611

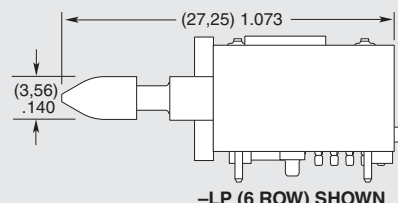
TEST DATA*	SEAF-RA/SEAM-02	SEAF-RA/SEAM-RA
Single-Ended	25 Gbps	24 Gbps
Differential Pair	26 Gbps	22 Gbps

* @ 3dB insertion loss. Test board losses deembedded from performance data.

Complete test data available at www.samtec.com?SEAF-RA or contact sig@samtec.com



* Note: Fixturing required to process eight and ten row options, see www.samtec.com/searayfixture



Note: Some sizes, styles and options are non-standard, non-returnable.